

PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

EPAS ID: PAT6519920

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	HONG KONG BEIDA JADE BIRD DISPLAY LIMITED	11/19/2020
RECEIVING PARTY DATA		
Name:	JADE BIRD DISPLAY (SHANGHAI) LIMITED	
Street Address:	1889 HONGYIN ROAD, PUDONG	
City:	SHANGHAI	
State/Country:	CHINA	
Postal Code:	201306	
PROPERTY NUMBERS Total: 5		
Property Type	Number	
Patent Number:	7098486	
Patent Number:	8916888	
Patent Number:	8956901	
Patent Number:	9171881	
Patent Number:	10191360	
CORRESPONDENCE DATA		
Fax Number:	(202)739-3001	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
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ATTORNEY DOCKET NUMBER:	123321-5000	
NAME OF SUBMITTER:	HANG ZHENG	
SIGNATURE:	/HANG ZHENG/	
DATE SIGNED:	01/27/2021	
Total Attachments: 3		

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PATENT/APPLICATION ASSIGNMENT AGREEMENT

WHEREAS Hong Kong Beida Jade Bird Display Limited, a corporation of China, whose post office address is Unit 7605, 76/F, The Center, 99 Queen's Road Central, Hong Kong, China (the "Assignor"), owns all right, title, and interest in and to all patents/patent applications identified in the attached Schedule A (collectively, the "Patents/Applications");

WHEREAS Jade Bird Display (Shanghai) Limited (上海显耀显示科技有限公司), a corporation of China, whose post office address is 1889 Hongyin Road, Pudong, Shanghai, China 201306 (the "Assignee"), is desirous of securing the entire right, title, and interest in and to the Patents/Applications in all countries throughout the world, the inventions claimed in the Patents/Applications, and the Letters Patent to be issued upon the patent applications identified in the attached Schedule A;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from the Assignee is hereby acknowledged, the Assignor has sold, assigned, transferred, and set over, and does hereby sell, assign, transfer, and set over unto the Assignee, and its lawful successors and assigns, its entire right, title, and interest in and to the Patents/Applications and the inventions claimed therein and all Patents/Applications that claim priority to the Patents/Applications, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof, and all rights to claim priority on the basis of such applications, and all applications for Letters Patent which may hereafter be filed for the inventions in any foreign country and all Letters Patent which may be granted on the inventions in any foreign country, and all extensions, renewals, and reissues thereof; and the Assignor hereby authorizes and requests the Director of Patents and Trademarks of the United States and any official of any foreign country whose duty it is to issue patents on applications as described above, to issue all Letters Patent of the inventions to the Assignee, and its successors and assigns, in accordance with the terms of this Assignment;

AND, the Assignor HEREBY covenants that it has the full right to convey the interest assigned by this Assignment, and the Assignor has not executed and will not execute any agreement in conflict with this Assignment;

AND, the Assignor HEREBY further covenants and agrees that it will, without further consideration, communicate with the Assignee, and its successors and assigns, any facts known to it respecting the inventions, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the titles to the inventions in said Assignee, and its successors or assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid the Assignee, and its successors and assigns, to obtain and enforce proper patent protection for the inventions in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, and its successors and assigns.

IN WITNESS WHEREOF, each of the parties has caused this Agreement to be executed by the signature of its duly authorized officer as of the date and year first written.



ASSIGNOR:
Hong Kong Beida Jade Bird Display Limited

By: Qiming LI

Signature: Qiming

Title: CEO

Date: 11/19/2020

ASSIGNEE:
Jade Bird Display (Shanghai) Limited

By: Qiming LI

Signature: Qiming

Title: CEO

Date: 11/19/2020



SCHEDULE A

Patent(s)/Patent Application(s):

Patent No.	Patent Application Ser. No.	Inventor(s) (First Name Last Name)	Title	Filing Date (MM-DD-YYYY)	Issue Date (MM-DD-YYYY)
U.S. 7,098,486	U.S. 11/019,223	Jeffrey Chen	LIGHT SOURCE ASSEMBLY HAVING HIGH-PERFORMANCE HEAT DISSIPATION MEANS	12-23-2004	08-29-2006
U.S. 8,916,888	U.S. 13/871,793	Jen-Shyan Chen	LED COMPONENT BY INTEGRATING EPITAXIAL STRUCTURE AND PACKAGE SUBSTRATE TOGETHER AND METHOD OF MANUFACTURING THE SAME	04-26-2013	12-23-2014
U.S. 8,956,901	U.S. 14/264,738	Jen-Shyan Chen	METHOD OF MANUFACTURING LED COMPONENT BY INTEGRATING EPITAXIAL STRUCTURE AND PACKAGE SUBSTRATE TOGETHER	04-29-2014	02-17-2015
U.S. 9,171,881	U.S. 14/542,881	Jen-Shyan Chen	LED COMPONENT BY INTEGRATING EPITAXIAL STRUCTURE AND PACKAGE SUBSTRATE TOGETHER AND METHOD OF MANUFACTURING THE SAME	11-17-2014	10-27-2015
U.S. 10,191,360	U.S. 15/394,817	Jen-Shyan Chen	MICROARRAY LED FLASH	12-30-2016	01-29-2019

